

ABSTRACT OF THE DISCLOSURE

MANUFACTURING APPARATUS OF SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

A manufacturing apparatus 10 of a semiconductor device includes: multiple processing heads 14f and 14s provided apart from each other in order to perform predetermined processing in different positions on a common lead frame 100, the processing heads 14f and 14s respectively including cameras 18f and 18s; and a controller 30 controlling driving of the processing heads, the controller positioning each of the processing heads 14f and 14s at a position where at least an optical offset OSo is canceled out. The controller takes an image of a paste Pf of one island If by the cameras 18f and 18s and acquires optical inspection images 40f and 40s respectively corresponding to the processing heads 14f and 14s before the positioning, and calculates, as the optical offset OSo, an amount of difference between the processing heads 14f and 14s in a relative positional relationship between the island If and the paste Pf shown in the optical inspection images 40f and 40s.

Figure 1